

ABSTRACT**COMPONENTS HAVING A FILM STRUCTURE AND METHODS OF
FORMING COMPONENTS HAVING A FILM STRUCTURE**

A method of forming a component having a film structure comprises thermally oxidising a first layer of a silicon substrate to form a compressive thermal oxidation silicon dioxide layer; and applying a layer comprising a nickel-titanium alloy to the first layer such that the first layer is located between the layer comprising a nickel-titanium alloy and the substrate. There is also disclosed a method of forming a component having a film structure comprising applying a first layer to a substrate to form an adhesive layer and applying a layer comprising a nickel-titanium alloy to the first layer such that the first layer is located between the layer comprising a nickel-titanium alloy and the substrate. There is further disclosed a component formed according to these methods and MEMS devices formed according to these methods.

[Fig. 1b]

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